

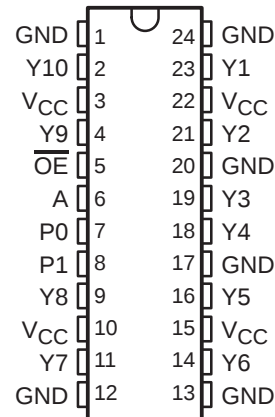
CDC2351

1-LINE TO 10-LINE CLOCK DRIVER WITH 3-STATE OUTPUTS

SCAS442D – FEBRUARY 1994 – REVISED SEPTEMBER 2000

- Low Output Skew, Low Pulse Skew for Clock-Distribution and Clock-Generation Applications
- Operates at 3.3-V V_{CC}
- LVTTTL-Compatible Inputs and Outputs
- Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Distributes One Clock Input to Ten Outputs
- Outputs Have Internal Series Damping Resistor to Reduce Transmission Line Effects
- Distributed V_{CC} and Ground Pins Reduce Switching Noise
- State-of-the-Art *EPIC-II B*[™] BiCMOS Design Significantly Reduces Power Dissipation
- Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages
- Available in Q-Temp Automotive High Reliability Automotive Applications Configuration Control / Print Support Qualification to Automotive Standards

DB OR DW PACKAGE
(TOP VIEW)



description

The CDC2351 is a high-performance clock-driver circuit that distributes one input (A) to ten outputs (Y) with minimum skew for clock distribution. The output-enable ($\overline{OE}$) input disables the outputs to a high-impedance state. Each output has an internal series damping resistor to improve signal integrity at the load. The CDC2351 operates at nominal 3.3-V V_{CC} .

The propagation delays are adjusted at the factory using the P0 and P1 pins. The factory adjustments ensure that the part-to-part skew is minimized and is kept within a specified window. Pins P0 and P1 are not intended for customer use and should be connected to GND.

The CDC2351 is characterized for operation from 0°C to 70°C. The CDC2351Q is characterized for operation over the full automotive temperature range of –40°C to 125°C.

FUNCTION TABLE

INPUTS		OUTPUTS
A	$\overline{OE}$	In
L	H	Z
H	H	Z
L	L	L
H	L	H



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

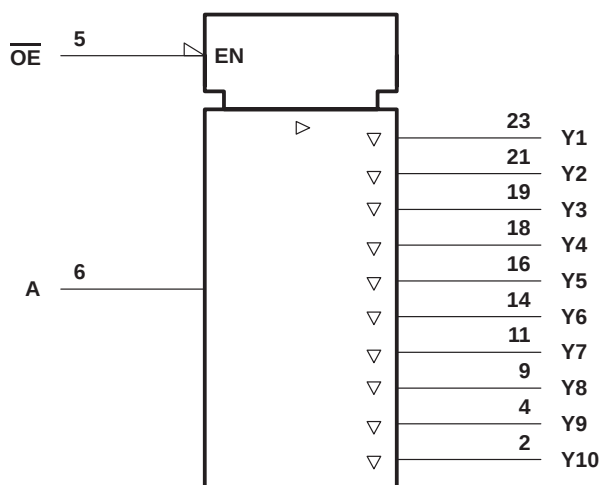


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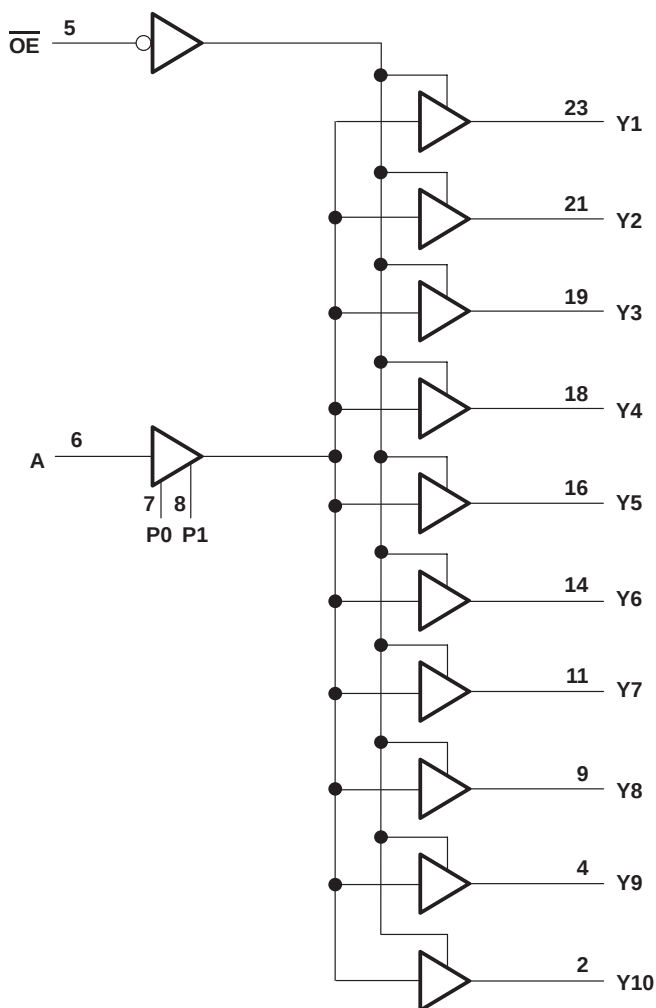
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



CDC2351

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V_O (see Note 1)	–0.5 V to 3.6 V
Current into any output in the low state, I_O	24 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_I < 0$)	–50 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2): DB package	0.65 W
DW package	1.7 W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.
 For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	3	3.6	V
V_{IH}	High-level input voltage	2		V
V_{IL}	Low-level input voltage		0.8	V
V_I	Input voltage	0	5.5	V
I_{OH}	High-level output current		–12	mA
I_{OL}	Low-level output current		12	mA
f_{clock}	Input clock frequency		100	MHz
T_A	Operating free-air temperature	CDC2351	0	70
		CDC2351Q	–40	125
				°C

NOTE 3: Unused pins (input or I/O) must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_{IK}	$V_{CC} = 3\text{ V}$,	$I_I = -18\text{ mA}$			–1.2	V
V_{OH}	$V_{CC} = 3\text{ V}$,	$I_{OH} = -12\text{ mA}$	2			V
V_{OL}	$V_{CC} = 3\text{ V}$,	$I_{OL} = 12\text{ mA}$			0.8	V
I_I	$V_{CC} = 3.6\text{ V}$,	$V_I = V_{CC}$ or GND			±1	μA
$I_O^\ddagger$	$V_{CC} = 3.6\text{ V}$,	$V_O = 2.5\text{ V}$	–7		–70	mA
I_{OZ}	$V_{CC} = 3.6\text{ V}$,	$V_{CC} = 3\text{ V}$ or 0			±10	μA
I_{CC}	$V_{CC} = 3.6\text{ V}$, $I_O = 0$, $V_I = V_{CC}$ or GND	Outputs high			0.3	mA
		Outputs low			15	
		Outputs disabled			0.3	
C_i	$V_I = V_{CC}$ or GND,	$V_{CC} = 3.3\text{ V}$, $f = 10\text{ MHz}$		4		pF
C_o	$V_O = V_{CC}$ or GND,	$V_{CC} = 3.3\text{ V}$, $f = 10\text{ MHz}$		6		pF

[‡] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.



CDC2351

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switching characteristics, $C_L = 50$ pF (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CDC2351			CDC2351Q		CDC2351		UNIT
			V _{CC} = 3.3 V, T _A = 25°C			V _{CC} = 3 V to 3.6 V, T _A = −40°C to 125°C		V _{CC} = 3 V to 3.6 V, T _A = 0°C to 70°C		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	3.8	4.3	4.8	1.1	11			ns
t _{PHL}			3.6	4.1	4.6	1	9.7			
t _{PZH}	OE	Y	2.4	4.9	6.0	1	12	1.8	6.9	ns
t _{PZL}			2.4	4.3	6.0	1	11.1	1.8	6.9	
t _{PHZ}	OE	Y	2.2	4.4	6.3	1	11.1	2.1	7.1	ns
t _{PLZ}			2.2	4.6	6.3	1	11.5	2.1	7.3	
t _{sk(o)}	A	Y		0.3	0.5		2.5		0.5	ns
t _{sk(p)}	A	Y		0.2	0.8		3		0.8	ns
t _{sk(pr)}	A	Y			1				1	ns
t _r	A	Y					2.5		2.5	ns
t _f	A	Y					2.5		2.5	ns

switching characteristics temperature and V_{CC} coefficients over recommended operating free-air temperature and V_{CC} range (see Note 4)

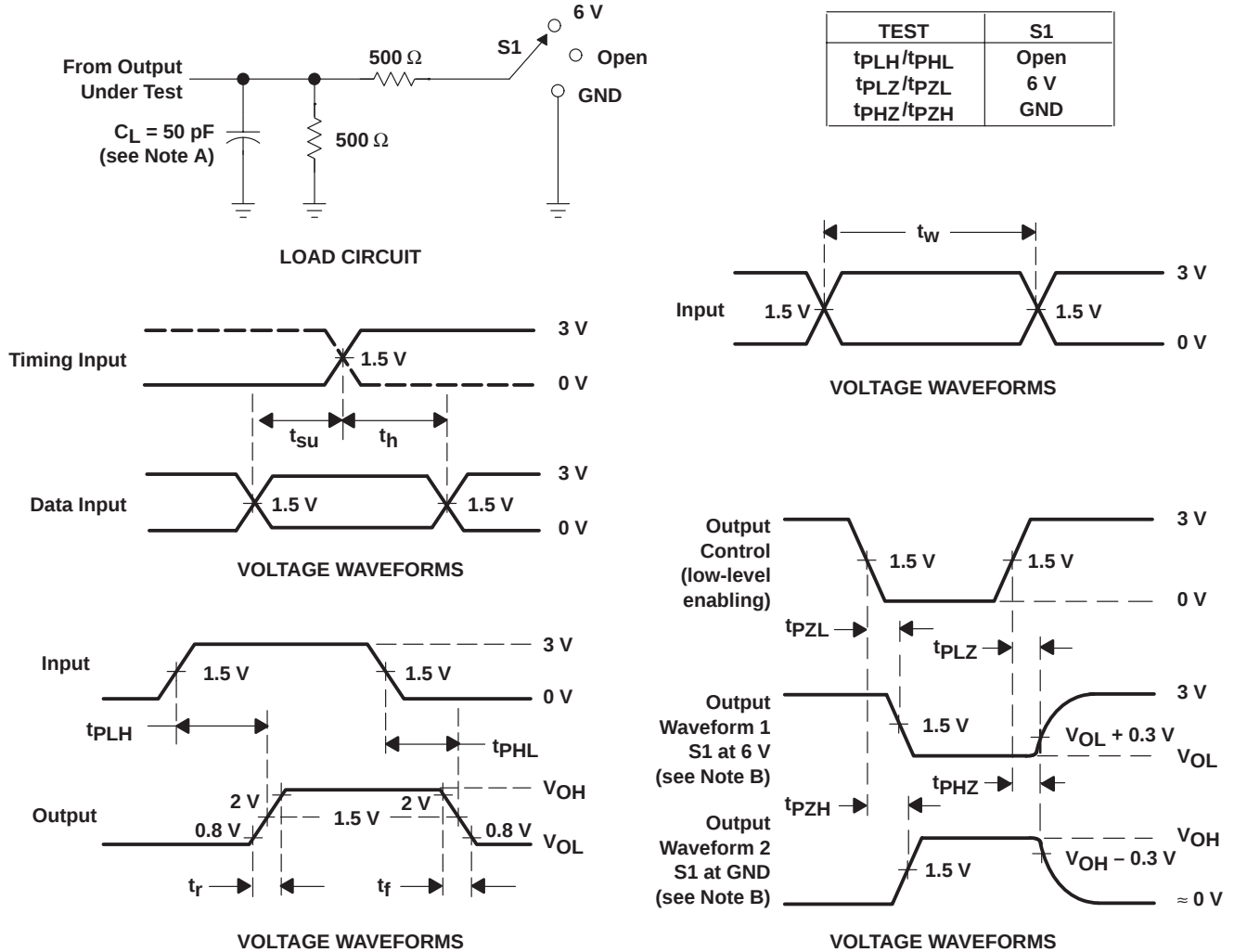
PARAMETER		FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$\alpha t_{PLH}(T)$	Average temperature coefficient of low to high propagation delay	A	Y		85 [†]	ps/ 10°C
$\alpha t_{PHL}(T)$	Average temperature coefficient of high to low propagation delay	A	Y		50 [†]	ps/ 10°C
$\alpha t_{PLH}(V_{CC})$	Average V_{CC} coefficient of low to high propagation delay	A	Y		-145 [‡]	ps/ 100 mV
$\alpha t_{PHL}(V_{CC})$	Average V_{CC} coefficient of high to low propagation delay	A	Y		-100 [‡]	ps/ 100 mV

[†] $\alpha t_{PLH}(T)$ and $\alpha t_{PHL}(T)$ are virtually independent of V_{CC} .

[‡] $\alpha t_{PLH}(V_{CC})$ and $\alpha t_{PHL}(V_{CC})$ are virtually independent of temperature.

NOTE 4: This data was extracted from characterization material and are not tested at the factory.

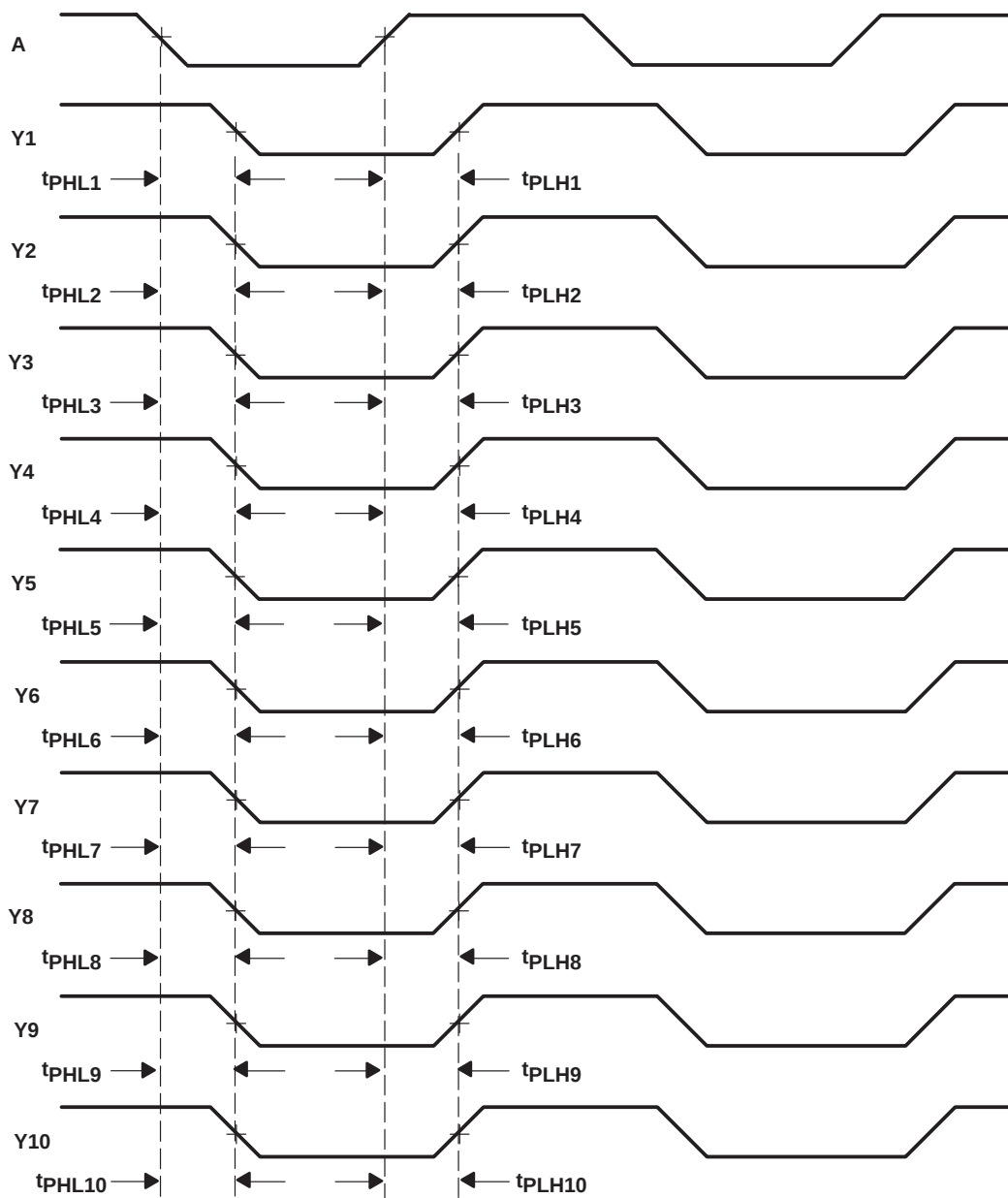
PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



NOTES: A. Output skew, $t_{sk(o)}$, is calculated as the greater of:

- The difference between the fastest and slowest of t_{PLHn} ($n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10$)
- The difference between the fastest and slowest of t_{PHLn} ($n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10$)

B. Pulse skew, $t_{sk(p)}$, is calculated as the greater of $|t_{PLHn} - t_{PHLn}|$ ($n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10$).

C. Process skew, $t_{sk(pr)}$, is calculated as the greater of:

- The difference between the fastest and slowest of t_{PLHn} ($n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10$) across multiple devices under identical operating conditions
- The difference between the fastest and slowest of t_{PHLn} ($n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10$) across multiple devices under identical operating conditions

Figure 2. Waveforms for Calculation of $t_{sk(o)}$, $t_{sk(p)}$, $t_{sk(pr)}$

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
CDC2351DB	Active	Production	SSOP (DB) 24	60 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	CK2351
CDC2351DB.B	Active	Production	SSOP (DB) 24	60 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	CK2351
CDC2351DBR	Active	Production	SSOP (DB) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	CK2351
CDC2351DBR.B	Active	Production	SSOP (DB) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	CK2351
CDC2351DW	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	CDC2351
CDC2351DW.B	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	CDC2351
CDC2351DWR	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	CDC2351
CDC2351DWR.B	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	CDC2351
CDC2351DWRG4	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	CDC2351
CDC2351QDB	Active	Production	SSOP (DB) 24	60 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CK2351Q
CDC2351QDB.B	Active	Production	SSOP (DB) 24	60 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CK2351Q
CDC2351QDBG4	Active	Production	SSOP (DB) 24	60 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CK2351Q
CDC2351QDBG4.B	Active	Production	SSOP (DB) 24	60 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CK2351Q
CDC2351QDBR	Active	Production	SSOP (DB) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CK2351Q
CDC2351QDBR.B	Active	Production	SSOP (DB) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CK2351Q
CDC2351QDBRG4	Active	Production	SSOP (DB) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CK2351Q
CDC2351QDBRG4.B	Active	Production	SSOP (DB) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CK2351Q

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF CDC2351, CDC2351-Q1 :

- Catalog : [CDC2351](#)
- Automotive : [CDC2351-Q1](#)
- Enhanced Product : [CDC2351-EP](#), [CDC2351-EP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDC2351DBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
CDC2351DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
CDC2351QDBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
CDC2351QDBRG4	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDC2351DBR	SSOP	DB	24	2000	353.0	353.0	32.0
CDC2351DWR	SOIC	DW	24	2000	350.0	350.0	43.0
CDC2351QDBR	SSOP	DB	24	2000	353.0	353.0	32.0
CDC2351QDBRG4	SSOP	DB	24	2000	353.0	353.0	32.0

TUBE

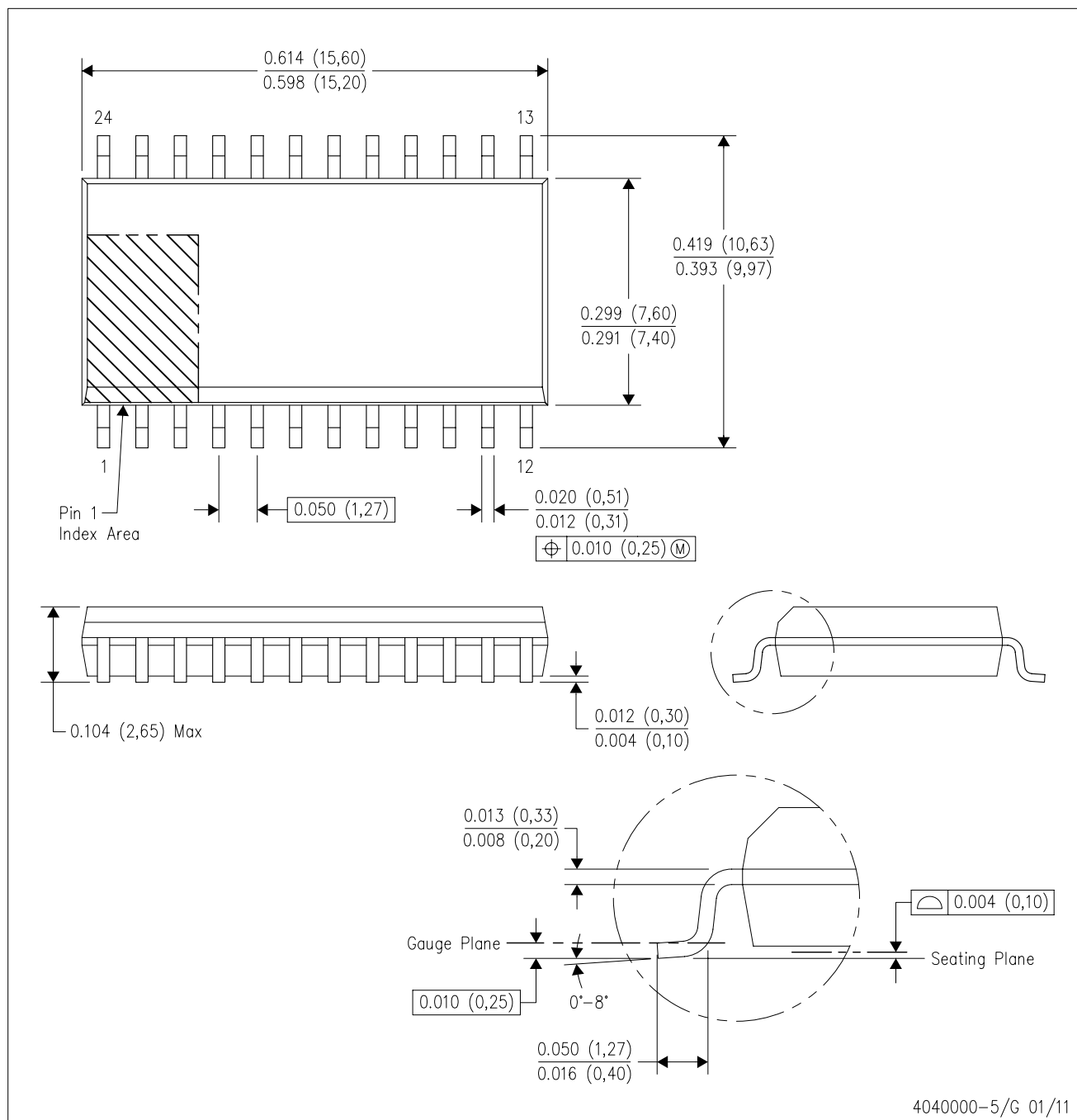


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
CDC2351DB	DB	SSOP	24	60	530	10.5	4000	4.1
CDC2351DB.B	DB	SSOP	24	60	530	10.5	4000	4.1
CDC2351DW	DW	SOIC	24	25	506.98	12.7	4826	6.6
CDC2351DW.B	DW	SOIC	24	25	506.98	12.7	4826	6.6
CDC2351QDB	DB	SSOP	24	60	530	10.5	4000	4.1
CDC2351QDB.B	DB	SSOP	24	60	530	10.5	4000	4.1
CDC2351QDBG4	DB	SSOP	24	60	530	10.5	4000	4.1
CDC2351QDBG4.B	DB	SSOP	24	60	530	10.5	4000	4.1

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-013 variation AD.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

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